



Material Content Data Sheet



Sales Product Name		TLE9250LE		Issued		25. January 2018		
MA#		MA001675864						
Package		PG-TSON-8-1		Weight*		26.86 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.790	2.94	2.94	29396	29396
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		110	
	non noble metal	zinc	7440-66-6	0.012	0.04		439	
	non noble metal	iron	7439-89-6	0.236	0.88		8788	
wire	non noble metal	copper	7440-50-8	9.586	35.68	36.61	356828	366165
	non noble metal	copper	7440-50-8	0.046	0.17	0.17	1730	1730
	encapsulation	organic material	carbon black	1333-86-4	0.031	0.11		1142
	plastics	epoxy resin	-	1.580	5.88		58819	
	inorganic material	silicondioxide	60676-86-0	13.730	51.12	57.11	511099	571060
leadfinish	non noble metal	tin	7440-31-5	0.382	1.42	1.42	14227	14227
plating	noble metal	silver	7440-22-4	0.043	0.16	0.16	1618	1618
glue	plastics	epoxy resin	-	0.106	0.40		3951	
	noble metal	silver	7440-22-4	0.318	1.19	1.59	11853	15804
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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